



# TU-902R

Core: TU-902R

Prepreg: TU-902P R

**TU-902R** is an advanced material designed for high speed computing, telecommunications, radio frequency super low loss filed applications. **TU-902R** electrical performance is competitive with PTFE-based, hydrocarbon-based very low loss materials, but capable for HLC with Sequential lamination or HDI design, also with excellent thermal reliability.

**TU-902R** laminates also exhibit excellent moisture resistance, Low CTE in Z-axis & X/Y-axis, superior chemical resistance, thermal stability, CAF resistance, and also compatible with modified FR-4 processes.

## Applications

- Radio frequency
- Backplane, High performance computing
- Line cards, Storage
- Servers, Telecom, Base station
- Office Routers

## Performance and Processing Advantages

- Excellent electrical and thermal properties
- Dielectric constant is 3.21 @ 10GHz
- Dissipation factor is 0.00107@ 10GHz
- Stable and flat Dk/Df performance over frequency and temperature variance.
- Compatible with modified FR-4 processes
- Excellent moisture resistance and Lead Free reflow process compatible
- Good Z-axis & X/Y-axis thermal expansion
- Superior dimensional stability, thickness uniformity and flatness
- Anti-CAF capability
- Excellent through-hole and soldering reliability
- Halogen Free

## Industry Approvals

- IPC-4101E Specification Number : 134
- UL File Number: Applying
- ANSI Grade: NA
- Flammability Rating: 94V-0
- Maximum Operating Temperature: NA

## Standard Availability

- Thickness: 0.002" [0.05mm] to 0.020" [0.508mm], available in sheet or panel form
- Copper Foil Cladding: 1/3 to 2 oz for built-up & double sides
- Prepregs: Available in roll or panel form
- Glass Styles: 1035, 1078 upon request.

The newly developed products are slightly modified and updated after more data has been collected.

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	Typical Values	Conditioning
<b>Thermal</b>		
Tg (DMA)	200 °C	E-2/105
Td (TGA)	430 °C	
CTE x/y axis	4 / 6 ppm/°C	Ambient to Tg (Tensile) Ambient to Tg (Compressing) Pre-Tg Post-Tg 50 to 260°C
	7 / 8 ppm/°C	
CTE z-axis α1	30 ppm/°C	
CTE z-axis α2	135 ppm/°C	
CTE z-axis	1.2 %	
Thermal Stress, Solder Float, 288°C	> 120 sec	A
T-260	> 60 min	E-2/105
T-288	> 60 min	
T-300	> 60 min	
Flammability	94V-0	E-24/125
<b>Electrical</b>		
Permittivity (RC70%) 10 GHz (SCR method)	3.21	E-2/105
Loss Tangent (RC70%) 10 GHz (SCR method)	0.00107	E-2/105
Volume Resistivity	> 10 <sup>10</sup> MΩ·cm	C-96/35/90
Surface Resistivity	> 10 <sup>8</sup> MΩ	C-96/35/90
Electric Strength	> 40 KV/mm	A
Dielectric Breakdown Voltage	> 50 KV	A
<b>Mechanical</b>		
Young's Modulus Warp Direction	23 GPa	A
Fill Direction	22 GPa	
Flexural Strength Lengthwise	> 60,000 psi	A
Crosswise	> 50,000 psi	
Peel Strength, 1 oz HVLP Cu foil	>3 lb/in	A
Moisture Absorption	0.05 %	E-1/105 + D-24/23

NOTE:

1. Property values are for information purposes only and not intended for specification.
2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.
3. This product is based on a patent pending technology.

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